

What is claimed is:

A method of attaching a semiconductor die to a lead frame comprising: providing a source of snap curable adhesive; providing a source of lead frames, each lead frame having an attaching surface; providing a source of semiconductor die, each semiconductor die having an active surface; applying said snap durable adhesive to a portions of one of the lead frames; and contacting said active surface of one of the semiconductor die with said portions of one of the lead frames having said snap curable adhesive thereon.

- The method of claim 1, further including the step of: 2. heating one of d semiconductor die.
- The method of claim 1, wherein said snap curable adhesive includes a snap 3. curable epoxy having a cure time of about one second.
- 4. The method of claim 1, wherein said snap curable adhesive includes an adhesive having a cure time of substantially one minute or less.
- 5. The method of claim 1, wherein said snap curable adhesive is applied to the portions of said one of the lead frames using a roller.
- 6. A method of attaching a semiconductor die to a lead frame comprising: providing a source of snap curable adhesive; providing a source of lead frames, each lead frame having an attaching surface; providing a source of semiconductor die, each semiconductor die having an active surface; applying said snap curable adhesive to a portions of the active surface of one of said

semiconductor die; and contacting said curable adhesive with portions of one of said lead frames.



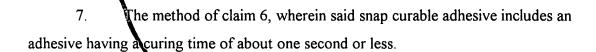
20

25





5



8. The method of claim 6, wherein said snap curable adhesive is applied to said active surface of one of said semiconductor devices in a predetermined pattern.